



Material Content Data Sheet



Sales Product Name		BSZ0904NSI		Issued		25. January 2018		
MA#		MA001005556						
Package		PG-TSDSON-8-25		Weight*		35.43 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.285	0.80	0.80	8032	8032
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		69	
	non noble metal	zinc	7440-66-6	0.010	0.03		278	
	non noble metal	iron	7439-89-6	0.197	0.56		5554	
wire	non noble metal	copper	7440-50-8	7.988	22.55	23.15	225499	231400
	noble metal	gold	7440-57-5	0.029	0.08	0.08	830	830
	encapsulation	organic material	carbon black	1333-86-4	0.038	0.11		1077
encapsulation	plastics	epoxy resin	-	1.965	5.55		55461	
	inorganic material	silicondioxide	60676-86-0	17.072	48.18	53.84	481914	538452
leadfinish	non noble metal	tin	7440-31-5	0.395	1.12	1.12	11158	11158
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	574	574
solder	non noble metal	tin	7440-31-5	0.009	0.03		266	
	noble metal	silver	7440-22-4	0.012	0.03		332	
	non noble metal	lead	7439-92-1	0.450	1.27	1.33	12702	13300
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		33	
	non noble metal	zinc	7440-66-6	0.005	0.01		133	
	non noble metal	iron	7439-89-6	0.094	0.27		2653	
	non noble metal	copper	7440-50-8	3.816	10.77	11.05	107717	110536
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		26	
	non noble metal	zinc	7440-66-6	0.004	0.01		103	
	non noble metal	iron	7439-89-6	0.073	0.21		2057	
	non noble metal	copper	7440-50-8	2.959	8.35	8.57	83532	85718
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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